

Packaging Regulations for Cologne Chip Products



The following regulations are valid for these products:

XHFC-1SU
XHFC-2SU

The chips are packed on trays.
Each tray carries 160 chips.



Due to quality reasons it is recommended to open vacuum packs only a little while before soldering.

To avoid rebaking of chips, only multiples of 1600 pcs. (= entire vacuum packs) should be ordered.

10 trays are inside a vacuum pack.

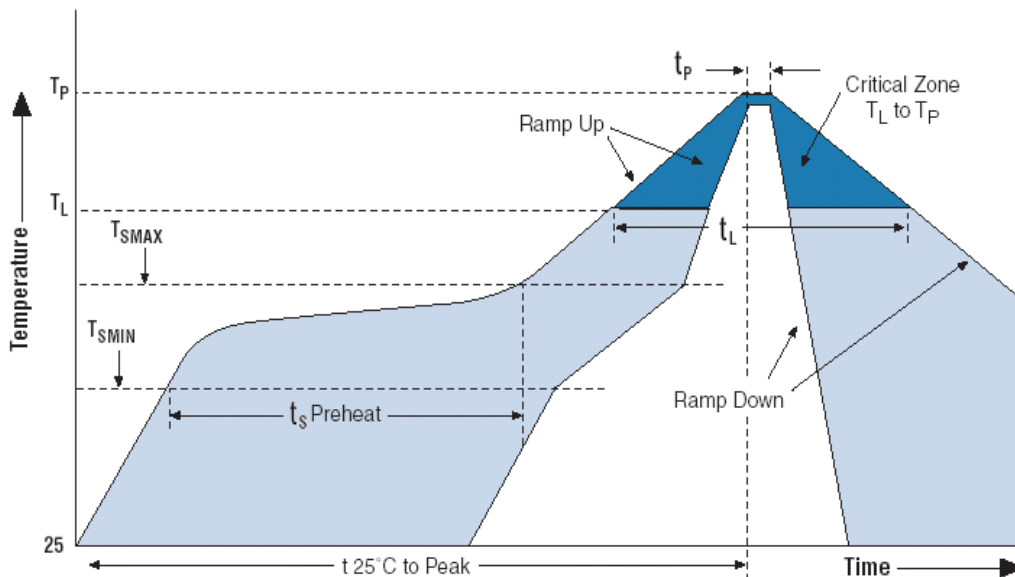


Each vacuum pack is put into a small box. This box is 1 lot (10 trays = 1600 pcs. of chips).

Weight: 2.1 kg
Dimensions: 36 cm x 15.4 cm x 7 cm

Soldering Reflow


Profile Feature	Sn-Pb eutectic assembly	Pb-free assembly
Average ramp-up rate (T_L to T_p)	3°C/second max.	3°C/second max.
Preheat <ul style="list-style-type: none"> - Temperature Min (T_{SMIN}) - Temperature Max (T_{SMAX}) - Time (min to max) (t_s) 	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
T_{SMAX} to T_L – Ramp-up Rate		3°C/second max
Time maintained above: <ul style="list-style-type: none"> - Temperature (T_L) - Time (t_L) 	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature (T_p)	240 +0/-5°C	260 +0/-5°C
Time within 5°C of actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



The recommended profiles for soldering reflow of XHFC-1SU / XHFC-2SU for **Sn-Pb eutectic** as well as **Pb-free assembly** mainly correspond to the commonly applied JEDEC Standard **JSTD-020C**. But to ensure best surface mounting quality, it is encouraged to use the provisions of **Pb-free assembly**. The table and graph above illustrate the respective soldering reflow.

Caution: Vacuum bags contain moisture sensitive devices!

Surface mount products may have a crack when thermal stress is applied during surface mount assembly if they have absorbed atmospheric moisture. It is recommended that these products are handled under specific conditions described as follows:

Package Type	Storage Condition after unpacking (as maximum)	Rebake Condition as minimum
 LQFP 64	Within 168 hours (30°C/60% RH) MSL 3	125°C 24 hours



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